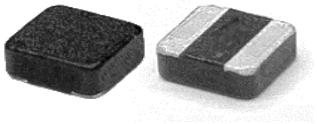
AFE2520 Series
Mini Molded Chip Power Inductors

FEATURES



- RoHS, Halogen Free and REACH Compliance
- High performance (Isat) realized by metal dust core.
- Low coil resistance with large currents.
- Operate temperature range .... －40℃～＋125℃(Including self temp. rise)

APPLICATIONS

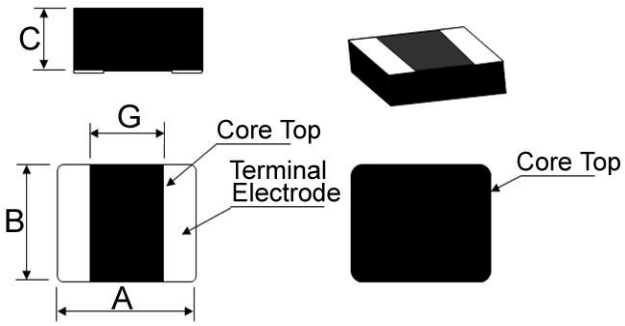
- Smart phone， pad
- Notebooks, VR, AR
- Portable gaming devices, Smart wear, Wi-Fi module

PRODUCT IDENTIFICATION

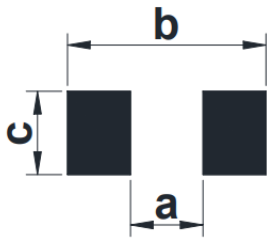
AFE 252010 S 2R2 M B T
① ② ③ ④ ⑤ ⑥ ⑦

① Series Name:Mini Molding Chip type power inductor
② Size Code: L*W*T
③ Feature Type:Standard
④ Initial inductance value: 2R2 = 2.2uH
⑤ Inductance Tolerance:M±20%
⑥ Coating color:B=Black
⑦ Packing： Tape & Reel

Dimensions: [mm]



Recommended Pattern



Series	A	G	B	C	b	a	c
AFE252055S	2.5±0.2	0.7±0.2	2.0±0.2	0.55Max.	2.60	0.70	2.10
AFE252075S	2.5±0.2	0.7±0.2	2.0±0.2	0.75Max.	2.60	0.70	2.10
AFE252008S	2.5±0.2	0.7±0.2	2.0±0.2	0.80Max.	2.60	0.70	2.10
AFE252010S	2.5±0.2	0.7±0.2	2.0±0.2	1.00Max.	2.60	0.70	2.10
AFE252012S	2.5±0.2	0.7±0.2	2.0±0.2	1.20Max.	2.60	0.70	2.10

Electrical Properties:

AFE252055S(2.5*2.0*0.55m)

P/N	L0(μH) @(0A) 1MHz	Rdc(mΩ)		Heat rating current Irms(A)		Saturation current Isat(A)	
		Typical	Max	Typical	Max	Typical	Max
AFE252055SR47MBT	0.47	42	49	5.5	5.2	3.5	3.2

AFE252075S(2.5*2.0*0.75m)

P/N	L0(μH) @(0A) 1MHz	Rdc(mΩ)		Heat rating current Irms(A)		Saturation current Isat(A)	
		Typical	Max	Typical	Max	Typical	Max
AFE252075S2R2MBT	2.2	78	90	2.3	2.0	2.6	2.4
AFE252075S100MBT	10.0	487	530	1.1	0.9	1.1	0.9

AFE252008S(2.5*2.0*0.8m)

P/N	L0(μH) @(0A) 1MHz	Rdc(mΩ)		Heat rating current Irms(A)		Saturation current Isat(A)	
		Typical	Max	Typical	Max	Typical	Max
AFE252008SR47MBT	0.47	22	27	6.5	6.0	6.0	5.3
AFE252008S1R0MBT	1.0	34	40	4.3	4.0	4.5	4.0
AFE252008S1R5MBT	1.5	64	75	3.4	3.0	3.5	3.0
AFE252008S2R2MBT	2.2	69	77	3.0	2.6	3.0	2.6
AFE252008S3R3MBT	3.3	150	180	2.5	2.1	2.5	2.1
AFE252008S100MBT	10	500	600	1.4	1.2	1.1	0.9

AFE252010S(2.5*2.0*1.0m)

P/N	L0(μH) @(0A) 1MHz	Rdc(mΩ)		Heat rating current Irms(A)		Saturation current Isat(A)	
		Typical	Max	Typical	Max	Typical	Max
AFE252010SR22MBT	0.22	12	17	6.8	6.5	8.6	7.9
AFE252010SR24MBT	0.24	12	17.5	6.7	6.4	8.5	7.8
AFE252010SR33MBT	0.33	13	19	6.5	6.2	7.6	7.2
AFE252010SR47MBT	0.47	15	22	6.1	5.6	6.9	6.5
AFE252010SR68MBT	0.68	23	27	5.6	5.0	5.9	5.5
AFE252010S1R0MBT	1.0	25	30	4.5	4.1	5.3	4.8
AFE252010S1R5MBT	1.5	45	55	3.4	3.0	4.3	3.9
AFE252010S2R2MBT	2.2	62	70	2.4	2.1	3.3	3.0
AFE252010S3R3MBT	3.3	86	100	2.5	2.1	2.8	2.5
AFE252010S4R7MBT	4.7	160	180	2.0	1.6	2.6	2.0

P/N	L0(μH) @(0A) 1MHz	Rdc(mΩ)		Heat rating current Irms(A)		Saturation current Isat(A)	
		Typical	Max	Typical	Max	Typical	Max
AFE252010S6R8MBT	6.8	270	320	1.6	1.4	2.4	1.9
AFE252010S100MBT	10.0	500	560	1.05	0.95	1.55	1.4
AFE252010S220MBT	22.0	1100	1300	0.85	0.6	1.1	0.9

AFE252012S(2.5*2.0*1.2mm)

P/N	L0(μH) @(0A) 1MHz	Rdc(mΩ)		Heat rating current Irms(A)		Saturation current Isat(A)	
		Typical	Max	Typical	Max	Typical	Max
AFE252012SR10MBT	0.1	6	10	12	10.5	13.5	12.5
AFE252012SR15MBT	0.15	7	11	11.5	10	13.0	12.0
AFE252012SR22MBT	0.22	9	14	8.2	7.6	9.6	9.0
AFE252012SR24MBT	0.24	10	15	8.0	7.5	9.3	8.8
AFE252012SR33MBT	0.33	11	17	6.8	6.4	8.3	7.8
AFE252012SR47MBT	0.47	13	19	6.5	6.0	7.5	7.0
AFE252012SR68MBT	0.68	17	23	6.3	5.5	6.5	6.0
AFE252012S1R0MBT	1.0	35	42	4.0	3.6	5.6	5.0
AFE252012S1R5MBT	1.5	44	50	3.7	3.2	4.5	4.1
AFE252012S2R2MBT	2.2	55	65	3.0	2.7	3.8	3.3
AFE252012S3R3MBT	3.3	80	97	2.3	1.8	3.0	2.7
AFE252012S4R7MBT	4.7	150	170	1.8	1.5	2.4	2.1
AFE252012S6R8MBT	6.8	245	270	1.6	1.4	2.0	1.7
AFE252012S100MBT	10.0	330	400	1.2	1.05	1.6	1.45
AFE252012S220MBT	22.0	740	800	1.2	1.1	1.1	1.0

Test remarks

Note 1.: All test data is referenced to 25 ℃ ambient.

Note 2.: Test Condition:1MHz, 1.0Vrms.

Note 3.: Irms:DC current (A) that will cause an approximate △T of 40 ℃.

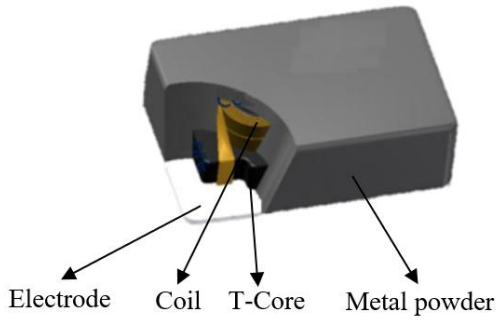
Note 4.: Isat:DC current (A) that will cause L0 to drop approximately 30%.

Note 5.: Operating Temperature Range -55℃ to + 125℃.

Note 6.: The part temperature (ambient + temp rise) should not exceed 125 under ℃ the worst case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provision all affect the part temperature. Part temperature should be verified in the end application.

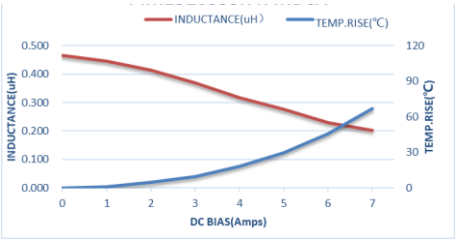
Note 7.: The rated current as listed is either the saturation current or the heating current depending on which value is lower.

Structure

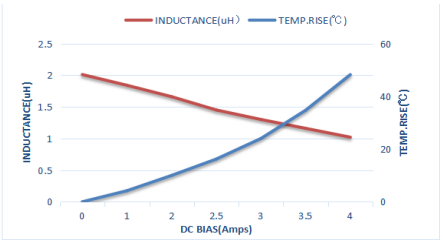


Current Characteristic

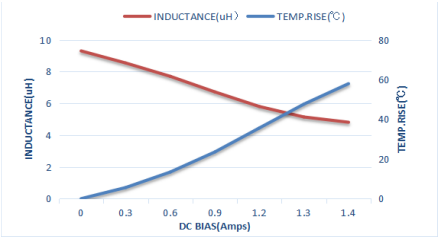
AFE252055SR47MBT



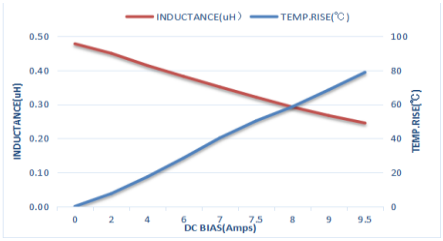
AFE252075S2R2MBT



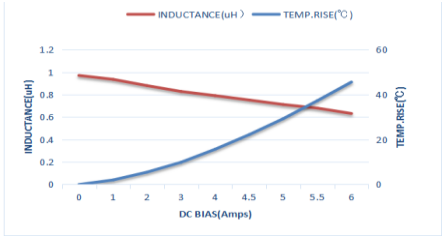
AFE252075S100MBT



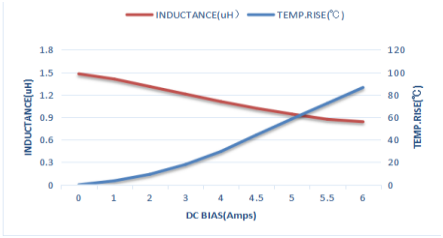
AFE252008SR47MBT



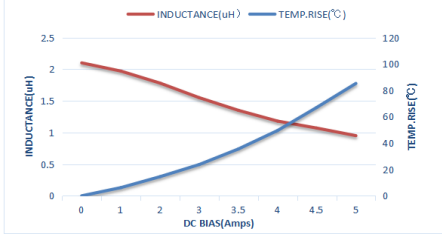
AFE252008S1R0MBT



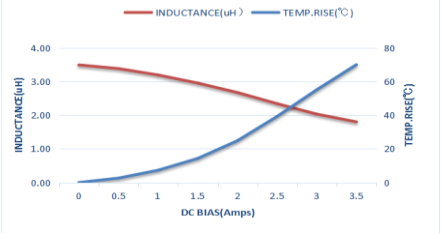
AFE252008S1R5MBT



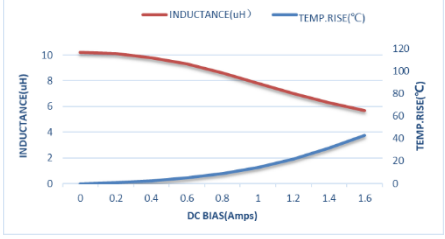
AFE252008S2R2MBT



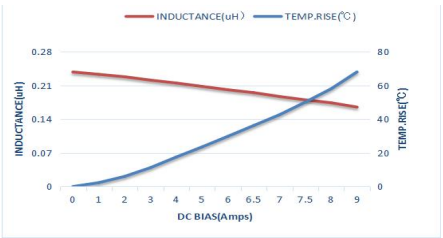
AFE252008S3R3MBT



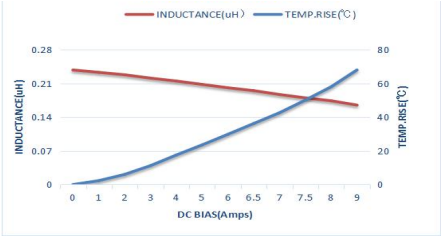
AFE252008S100MBT



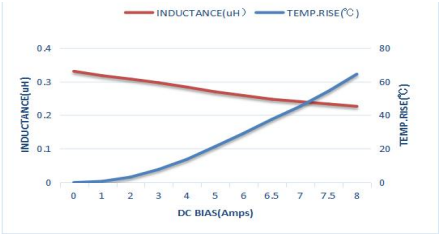
AFE252010SR22MBT



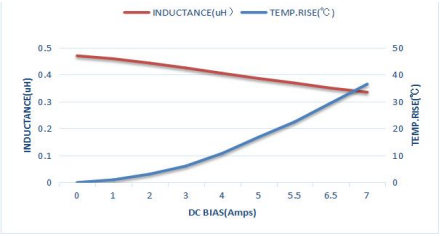
AFE252010SR24MBT



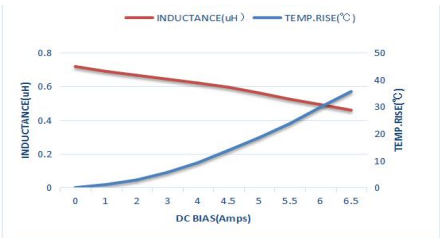
AFE252010SR33MBT



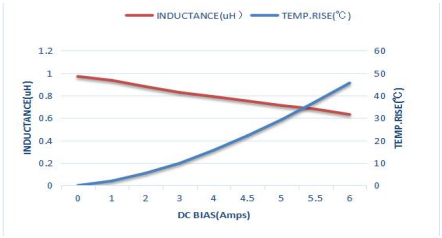
AFE252010SR47MBT



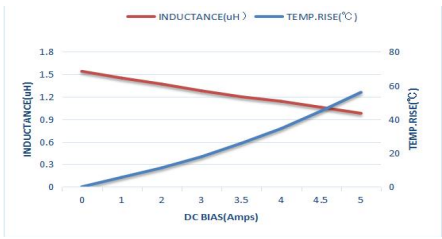
AFE252010SR68MBT



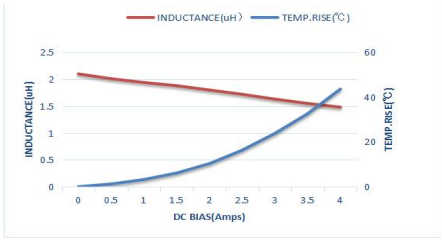
AFE252010S1R0MBT



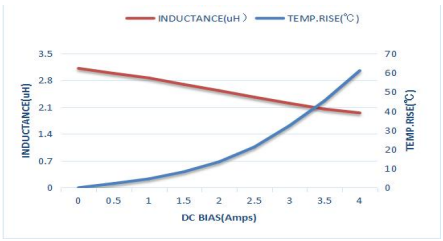
MTQH252010S1R5MBT



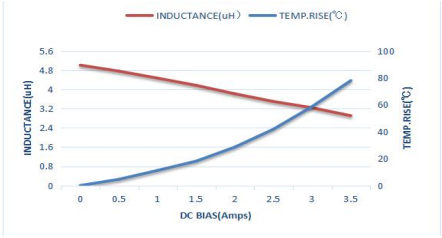
MTQH252010S2R2MBT



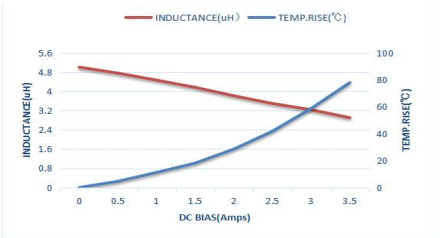
MTQH252010S3R3MBT



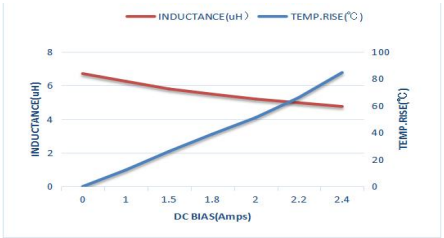
AFE252010S4R7MBT



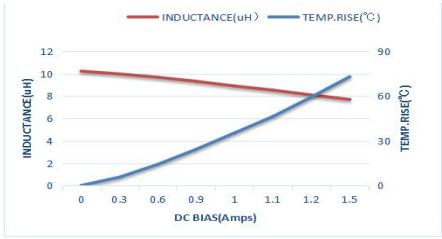
AFE252010S4R7MBTA



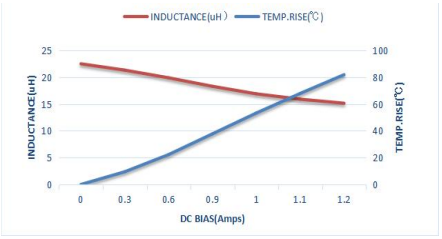
AFE252010S6R8MBT



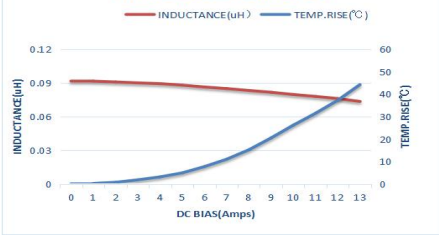
AFE252010S100MBT



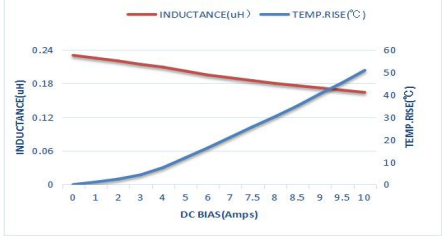
AFE252010S220MBT



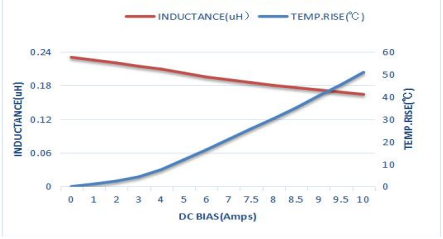
AFE252012SR10MBT



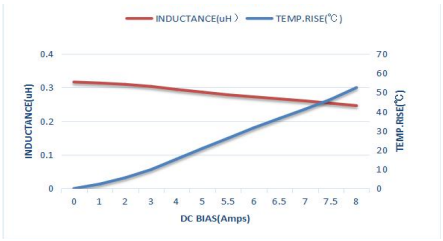
AFE252012SR22MBT



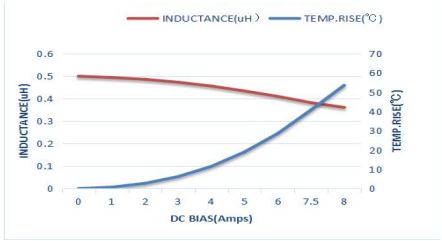
AFE252012SR24MBT



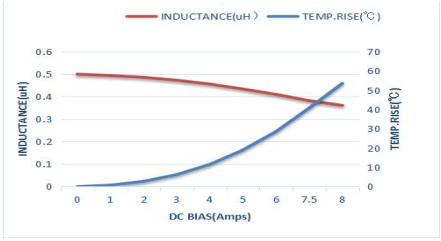
AFE252012SR33MBT



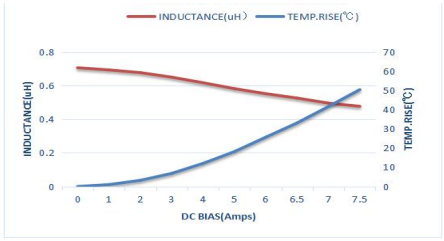
AFE252012SR47MBT



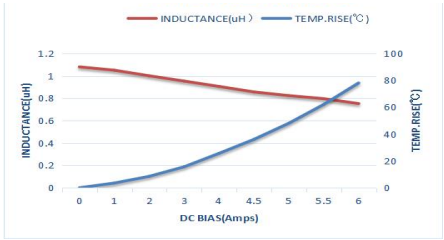
AFE252012SR47MBTD



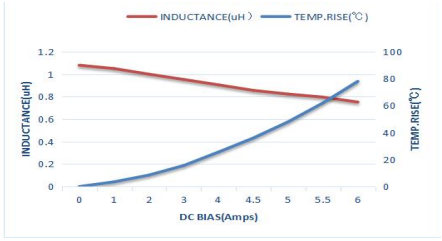
AFE252012SR68MBT



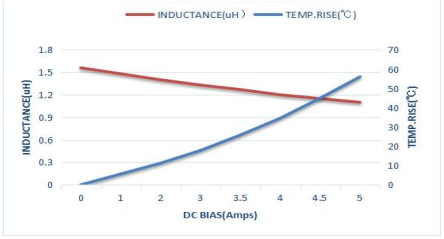
AFE252012S1R0MBT



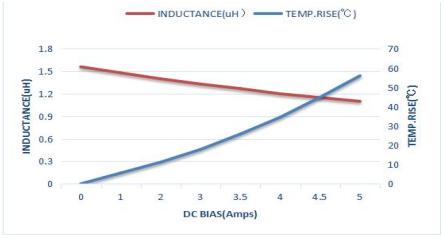
AFE252012S1R0MBTA



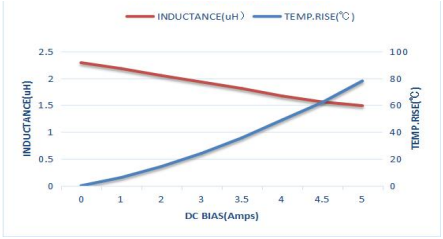
AFE252012S1R5MBT



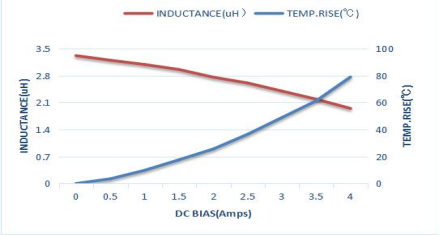
AFE252012S1R5MBTA



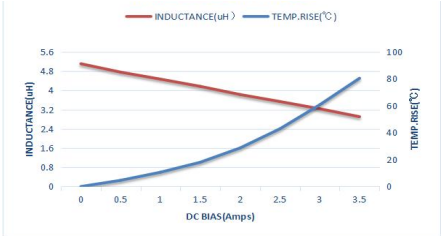
AFE252012S2R2MBT



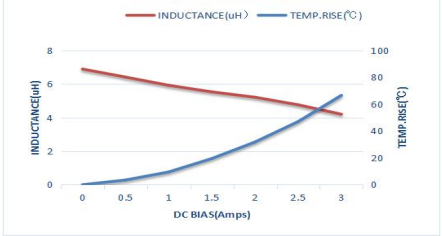
AFE252012S3R3MBT



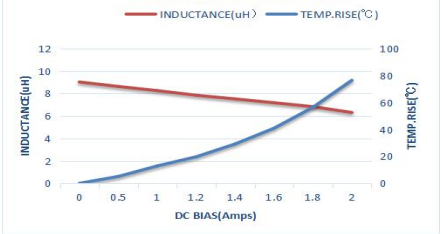
AFE252012S4R7MBT



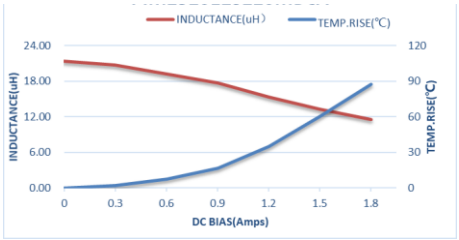
AFE252012S6R8MBT



AFE252012S100MBT



AFE252012S220MBT



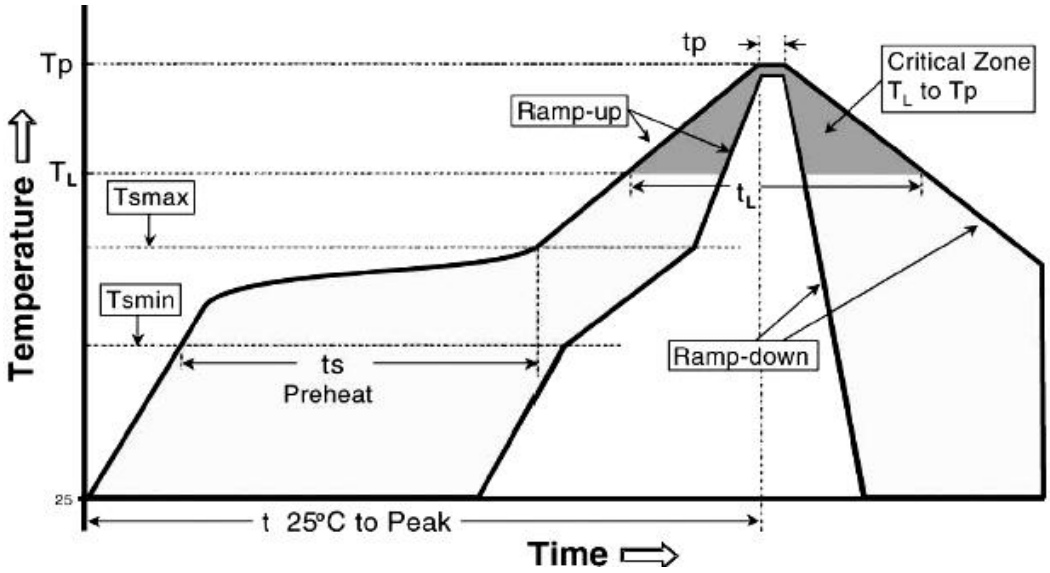
Reliability

Item	Requirements	Test Methods and Remarks
Insulation Resistance	≥100MΩ	100 VDC between inductor coil and The middle of the top surface of the body for 60 seconds.
Solderability	90% or more of electrode area shall be coated by new solde.	Dip pads in flux . Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free). Solder Temperature: 245±5℃. Immersion Time: (5±1) s.
Resistance to Soldering Heat	No visible mechanical damage. Inductance change: Within ±10.	Dip pads in flux. Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free). Solder Temperature: 260±5℃. Immersion Time: 10±1sec.
Adhesion of teral electrode	Strong bond between the pad and the core, without come off PCB.	Inductors shall be subjected to (260±5)℃ for (20±5)s Soldering in the base whit 0.3mm solder. And then aplombelectrode way plus tax 10 N for (10±1) seconds.
High temperature	No case deformation or change in appearance. Inductance change: Within ±10%	Temperature: 125±2℃. Time : 1000 hours. Measurement at 24±4 hours after test conclusion.
Low temperature	No visible mechanical damage. Inductance change: Within ±10%	Temperature: -40±2℃. Time : 1000 hours. Measurement at 24±4 hours after test conclusion.
Thermal shock	No visible mechanical damage. Inductance change: Within ±10%	The test sample shall be placed at (-55±3)℃ and (125±3)℃ for (30±3) , different temperature conversion time is 2~3 utes. The temperature cycle shall be repeated 32 cycles. Placed at room temperature for 2 hours, within 48±4 hours of testing.
Temperature characteristic	Inductance change Pc-b,Pc-d: Within ±20%	a：+20 ℃ （30~45） → b: -40 ℃ （30~45） → c: +20 ℃ （30~45） → d: +125 ℃ （30~45） → e: +20 ℃ （30~45） $P_{c\text{-}b}=\frac{L_b-L_c}{L_c}\times 100\%$; $P_{c\text{-}d}=\frac{L_d-L_c}{L_c}\times 100\%$
Static Humidity	No visible mechanical damage. Inductance change: Within ±10%	Inductors shall be subjected to (95±3)%RH . at(60±2)℃ for (1000±4) h. Placed at room temperature for 2 hours, within 48 hours of testing.
	No visible mechanical damage. Inductance change: Within ±10%	Inductors shall be store at (85±2)℃ for (1000±4) hours with Irms applied. Placed at room temperature for 2 hours, within 48 hours of testing

Soldering Condition

(This is for recommendation, please customer perform adjustment according to actual application)

Recommend Reflow Soldering Profile：(solder : Sn96.5 / Ag3 / Cu0.5)



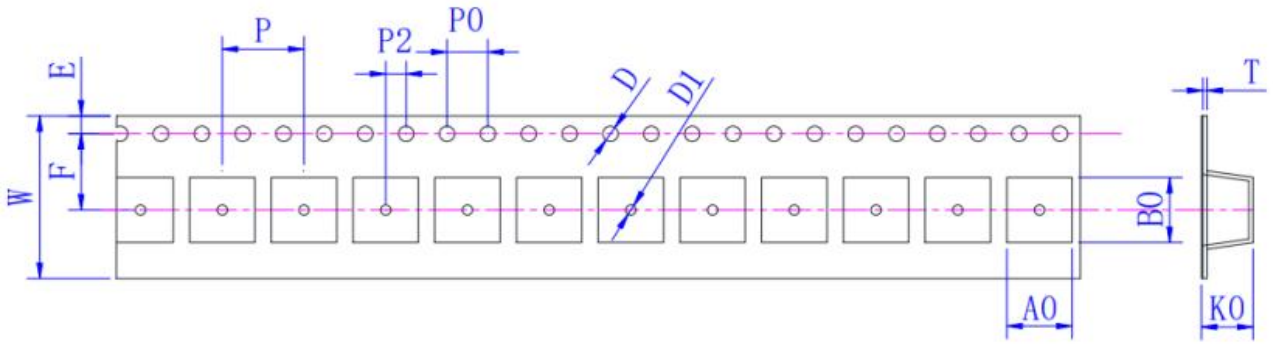
Profile Feature	Lead (Pb)-Free solder
Preheat：	
Temperature Min (Ts_{min})	150℃
Temperature Max (Ts_{max})	200℃
Time (Ts_{min} to Ts_{max}) (ts)	60 -120 seconds
Average ramp-up rate：	
(Ts max to Tp)	3℃ / second max.
Time maintained above :	
Temperature (T_L)	217℃
Time (t_L)	60-150 seconds
Peak Temperature (Tp)	260℃
Time within $^{+0}_{-5}$℃ of actual peak Temperature (tp)[2]	10 seconds
Ramp-down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8minutes max.

Allowed Re-flow times : 2 times

Remark : To avoid discoloration phenomena of chip on terminal electrodes, please use N_2 Re-flow furnace .

Packing

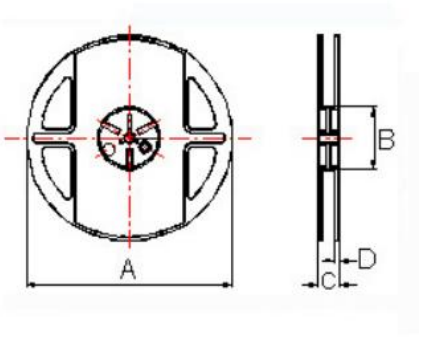
Dimension of plastic taping: (Unit: mm)



Series	W ±0.30	A0 ±0.05	B0 +0.1/-0	D +0.1/-0	D1 Min	E ±0.10	F ±0.10	K0 ±0.05	P0 ±0.10	P2 ±0.10	P ±0.10	T ±0.05
252075/08	8.00	2.40	2.80	1.50	1.0	1.75	3.50	1.00	4.00	2.00	4.00	0.23
252010	8.00	2.40	2.80	1.50	1.0	1.75	3.50	1.20	4.00	2.00	4.00	0.23
252012	8.00	2.40	2.80	1.50	1.0	1.75	3.50	1.40	4.00	2.00	4.00	0.23

Dimension of Reel：(Unit: mm)

Type	A ±0.5	B ±0.5	C ±0.5	D ±1
All	178	60	12	1.5



Packing Quantity：3000pcs/Reel